40V Nch+Nch Power MOSFET

V _{DSS}	40V
R _{DS(on)} (Max.)	85mΩ
I _D	±5.2A
P_D	3W

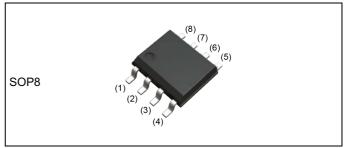
Features

- 1) Low on resistance
- 2) Small Surface Mount Package
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen Free

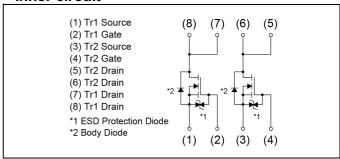
Application

Switching

Outline



•Inner circuit



Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	ТВ
	Marking	SH8K25

ullet **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) <Tr1 and Tr2>

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	40	V	
Continuous drain current	I _D *1	±5.2	Α	
Pulsed drain current	I _{DP} *2	±8	Α	
Gate - Source voltage	V _{GSS}	±12	V	
Avalanche current, single pulse	I _{AS} *3	8	Α	
Avalanche energy, single pulse	E _{AS} *3	0.48	mJ	
	P _D *1	3		
Power dissipation (total)	P _D *4	2	W	
	P _D *5	1.4		
Junction temperature	T _j	150	°C	
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C	

●Thermal resistance

Downwater	Currele el	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion, embient (total)	R _{thJA} *4	-	-	62.5	°C/W
Thermal resistance, junction - ambient (total)	R _{thJA} *5	-	-	89.2	C/VV

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Davanastav	Cumbal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UTIIL	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	40	-	-	V	
Breakdown voltage	ΔV _{(BR)DSS}	I _D = 1mA	_	27.3	-	mV/°C	
temperature coefficient	ΔT_{j}	referenced to 25°C	-	21.5	-	IIIV/ C	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 40V, V_{GS} = 0V$	-	-	1	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	±10	μA	
Gate threshold voltage	V _{GS(th)}	V _{DS} = 10V, I _D = 1mA	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-4.6	-	mV/°C	
Static drain - source	D *6	V _{GS} = 10V, I _D = 5.2A	-	60	85	0	
on - state resistance	R _{DS(on)} *6	V _{GS} = 4.5V, I _D = 4.0A	-	80	112	mΩ	
Gate resistance	R_G	f = 1MHz, open drain	-	19	-	Ω	
Forward Transfer Admittance	Y _{fs} *6	V _{DS} = 10V, I _D = 4A	1.0	-	-	S	

^{*1} Pw ≤ 1s, Limited only by maximum temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \simeq 10 μ H, V_{DD} = 20V, R_G = 25 Ω , Starting T_i = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Mounted on a ceramic board (30×30×0.8mm)

^{*5} Mounted on a Cu board (40×40×0.8mm)

^{*6} Pulsed

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Daramatar	Cymala al	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	UIIIL	
Input capacitance	C _{iss}	V _{GS} = 0V	-	100	-		
Output capacitance	C _{oss}	V _{DS} = 10V	-	50	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	15	-		
Turn - on delay time	t _{d(on)} *6	V _{DD} ≈ 20V,V _{GS} = 10V	-	6	-		
Rise time	t _r *6	I _D = 2A	-	5	-		
Turn - off delay time	t _{d(off)} *6	$R_L = 10\Omega$	-	17	-	ns	
Fall time	t _f *6	$R_G = 10\Omega$	-	3	-		

ullet Gate charge characteristics (T_a = 25°C) <Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit
raianietei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*6}		-	1.7	-	
Gate - Source charge	Q _{gs} *6	$V_{DD} \approx 20V$, $I_D = 4A$ $V_{GS} = 5V$	-	0.9	-	nC
Gate - Drain charge	Q _{gd} *6	1.00	-	0.3	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit
raianietei	Symbol	Conditions	Min.	Тур.	Max.	Offit
Continuous forward current	I _S	T - 25°C	-	-	1.6	^
Pulse forward current	I _{SP} *2	T _a = 25°C	-	-	8	А
Forward voltage	V _{SD} *6	V _{GS} = 0V, I _S = 4A	-	-	1.2	V

Fig.1 Power Dissipation Derating Curve

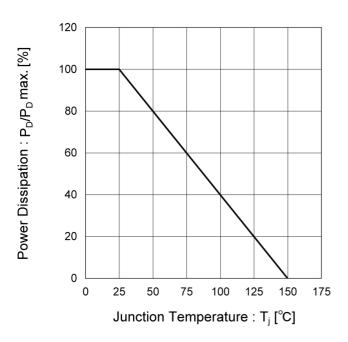
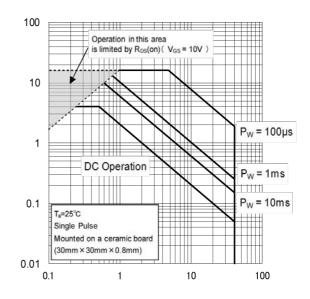


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

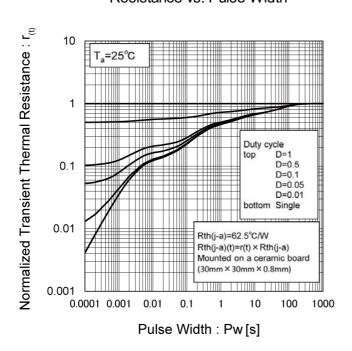
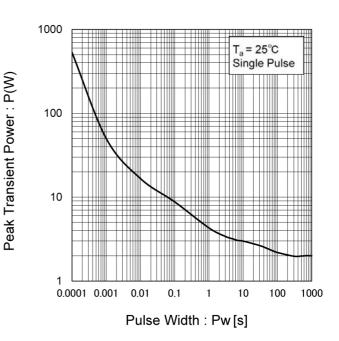


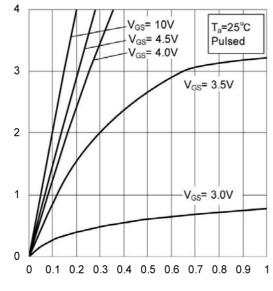
Fig.4 Single Pulse Maximum Power dissipation



Drain Current : I_D [A]

• Electrical characteristic curves

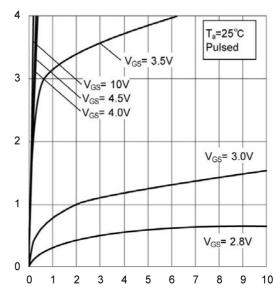
Fig.5 Typical Output Characteristics(I)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

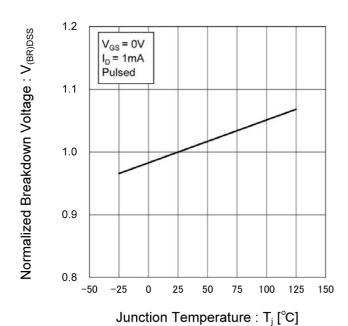


Fig.8 Typical Transfer Characteristics

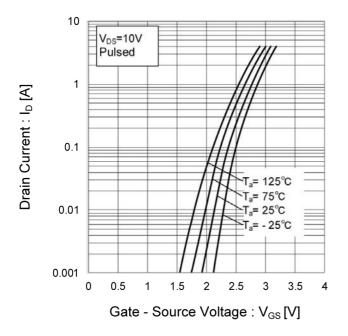
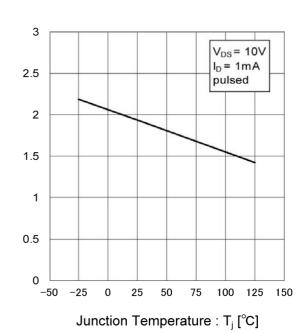


Fig.9 Gate Threshold Voltage vs.
Junction Temperature



Gate Threshold Voltage: VGS(th) [V]

Fig.10 Forward Transfer Admittance vs.
Drain Current

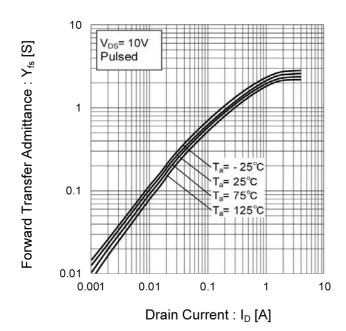


Fig.11 Drain Current Derating Curve

120 100 Drain Current Dissipation 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

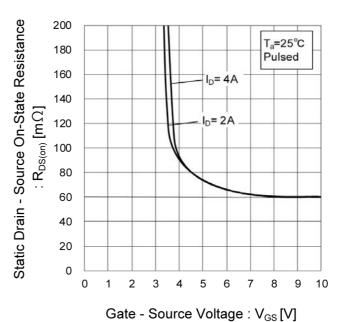


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

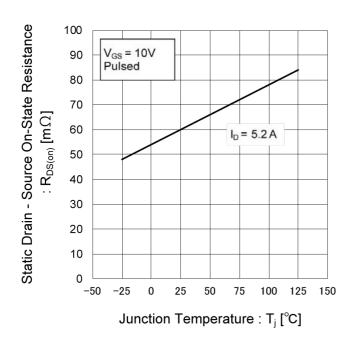


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

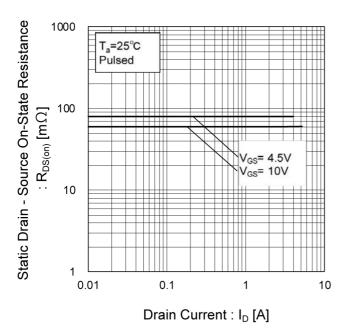
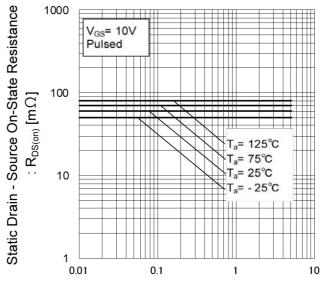


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)



Drain Current: ID [A]

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

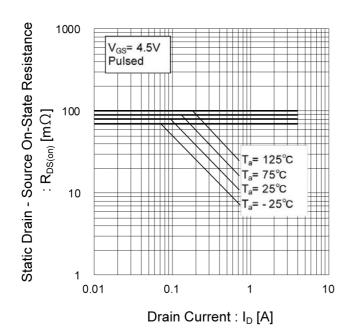
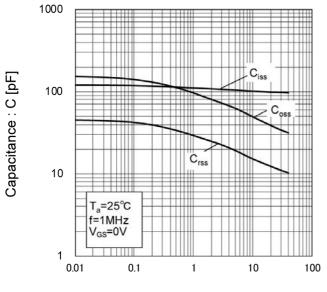


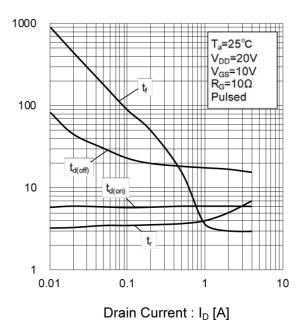
Fig.17 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics



Source voltage . V_{DS}[V]

Switching Time : t [ns]

Fig.19 Dynamic Input Characteristics

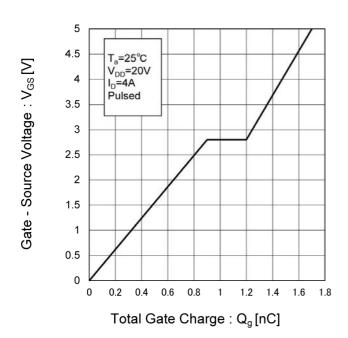
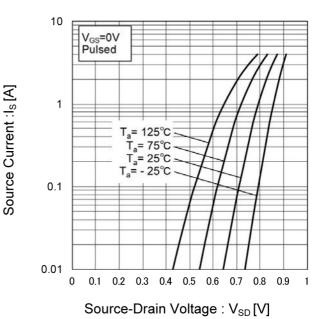


Fig.20 Source Current vs.

Source Drain Voltage



• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

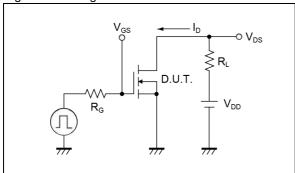


Fig.2-1 Gate Charge Measurement Circuit

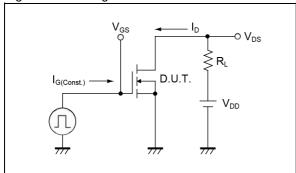


Fig.3-1 Avalanche Measurement Circuit

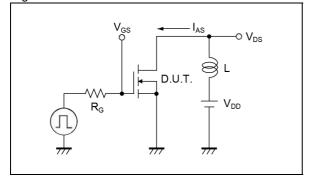


Fig.1-2 Switching Waveforms

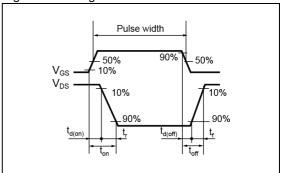


Fig.2-2 Gate Charge Waveform

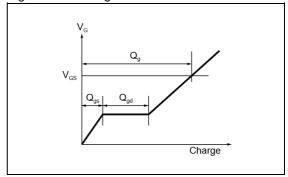
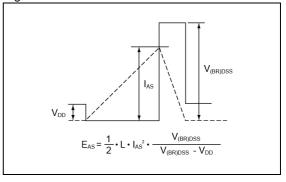
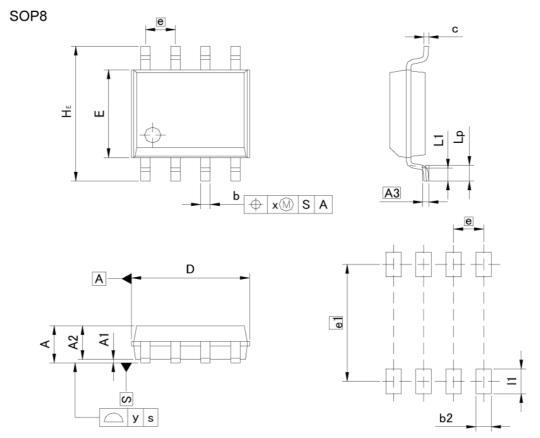


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
Α	<u></u>	1.75	= 1	0.069
A1	0.	15	0.0	06
A2	1.40	1.60	0.055	0.063
A3	0.	25	0.0	10
b	0.30	0.50	0.012	0.020
С	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
E	3.75	4.05	0.148	0.159
е	1.	27	0.050	
HE	5.70	6.30	0.224	0.248
L1	0.40	0.60	0.016	0.024
Lp	0.65	0.85	0.026	0.033
х	0.	15	0.006	
У	0.10		0.0	04
DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX

 DIM
 MIN
 MAX
 MIN
 MAX

 b2
 0.65
 0.026

 e1
 5.15
 0.203

 l1
 1.15
 0.045

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
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